





#### **DUAL SURFACE MOUNT SWITCHING DIODE**

#### **Features**

- · Fast Switching Speed: Maximum of 4ns
- Low Capacitance: Maximum of 2.0pF
- Small Surface Mount Package
- For General Purpose Switching Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

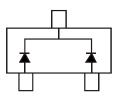
### **Mechanical Data**

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound, Note
  5. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe) (3)
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)





Top View



Top View Internal Schematic

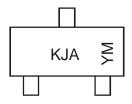
### Ordering Information (Notes 4 & 5)

Part Number	Qualification	Case	Packaging
BAV70W-7-F	Commercial	SOT323	3000/Tape & Reel
BAV70WQ-7-F	Automotive	SOT323	3000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.
- 5. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb<sub>2</sub>O<sub>3</sub> Fire Retardants.

# **Marking Information**



KJA = Product Type Marking Code YM = Date Code Marking

Y = Year ex: Z = 2012 M = Month ex: 9 = September

#### Date Code Key

Year	2000	2001	2002	2003		2012	2013	201	4 201	5 2016	2017	2018	2019
Code	L	М	N	Р		Z	Α	В	С	D	Е	F	G
Month	Jan	Feb	Mar	Apr	Ма	y J	un	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5		6	7	8	9	0	N	D



## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	$V_{RM}$	100	V	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	75	V	
RMS Reverse Voltage	$V_{R(RMS)}$	53	V	
Forward Continuous Current (Note 6)	I <sub>FM</sub>	300	mA	
Non-Repetitive Peak Forward Surge Current (Note 6) @ t = 1.0µs @ t = 1.0x		I <sub>FSM</sub>	2.0 1.0	Α

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P <sub>D</sub>	200	mW
Thermal Resistance Junction to Ambient Air (Note 6)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

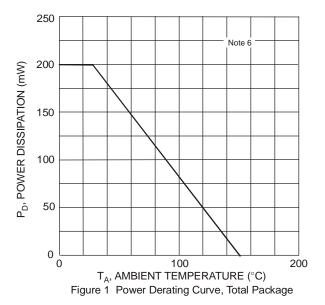
## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

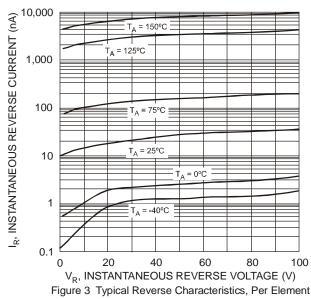
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	75	1	V	$I_R = 100\mu A$
Forward Voltage	V <sub>F</sub>		0.715 0.855 1.0 1.25	V	I <sub>F</sub> = 1.0mA I <sub>F</sub> = 10mA I <sub>F</sub> = 50mA I <sub>F</sub> = 150mA
Reverse Current (Note 7)	I <sub>R</sub>		2.5 50 30 25	μΑ μΑ μΑ nA	$V_R = 75V$ $V_R = 75V$ , $T_J = +150^{\circ}C$ $V_R = 25V$ , $T_J = +150^{\circ}C$ $V_R = 20V$
Total Capacitance	Ст	_	2.0	pF	$V_R = 0, f = 1.0MHz$
Reverse Recovery Time	t <sub>rr</sub>		4.0	ns	$I_F = I_R = 10 \text{mA},$ $I_{rr} = 0.1 \text{ x } I_R, R_L = 100 \Omega$

Notes: 6. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com.

<sup>7.</sup> Short duration pulse test used to minimize self-heating effect.







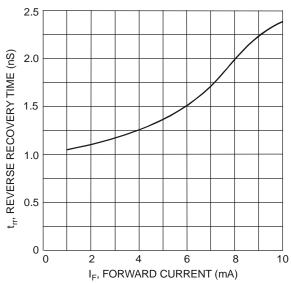
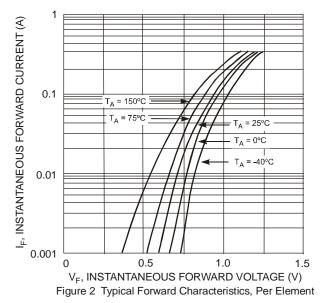


Figure 5 Reverse Recovery Time vs. Forward Current, Per Element



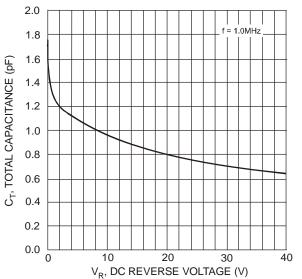
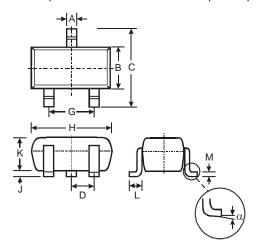


Figure 4 Total Capacitance vs. Reverse Voltage, Per Element



# **Package Outline Dimensions**

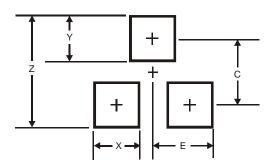
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT323							
Dim	Min	Max	Тур				
Α	0.25	0.40	0.30				
В	1.15	1.35	1.30				
С	2.00	2.20	2.10				
D	-	-	0.65				
G	1.20	1.40	1.30				
Н	<b>H</b> 1.80 2.20		2.15				
J	0.0	0.10	0.05				
K	0.90	1.00	1.00				
L	0.25	0.40	0.30				
М	0.10	0.18	0.11				
α	0°	8°	-				
All Dimensions in mm							

# Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.8
Х	0.7
Y	0.9
С	1.9
E	1.0



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